

High-Speed CAN Transceiver with Silent Mode - CAN FD Ready

Features

- Fully ISO 11898-2, ISO 11898-2: 2016 and SAE J2962-2 Compliant
- CAN FD Ready
- Communication Speed up to 5 Mbit/s
- Low Electromagnetic Emission (EME) and High Electromagnetic Immunity (EMI)
- Differential Receiver with Wide Common Mode Range
- Compatible to 3.3V and 5V Microcontrollers
- Functional Behavior Predictable under all Supply Conditions
- Transceiver Disengages from the Bus When Not Powered-up
- RXD Recessive Clamping Detection
- High Electrostatic Discharge (ESD) Handling Capability on the Bus Pins
- Bus Pins Protected against Transients in Automotive Environments
- Transmit Data (TXD) Dominant Time-out Function
- Undervoltage Detection on VCC and VIO Pins
- CANH/CANL Short-circuit and Overtemperature Protected
- Fulfills the OEM "Hardware Requirements for LIN, CAN and FlexRay Interfaces in Automotive Applications", Rev. 1.3
- Qualified According to AEC-Q100
- Two Ambient Temperature Grades:
 - ATA6564-GAQW1 and ATA6564-GBQW1 up to $T_{amb} = +125^{\circ}\text{C}$
 - ATA6564-GAQW0 and ATA6564-GBQW0 up to $T_{amb} = +150^{\circ}\text{C}$
- Packages: 8-pin SOIC, 8-pin VDFN with Wettable Flanks (Moisture Sensitivity Level 1)

Applications

Classical CAN and CAN FD networks in Automotive, Industrial, Aerospace, Medical and Consumer applications.

General Description

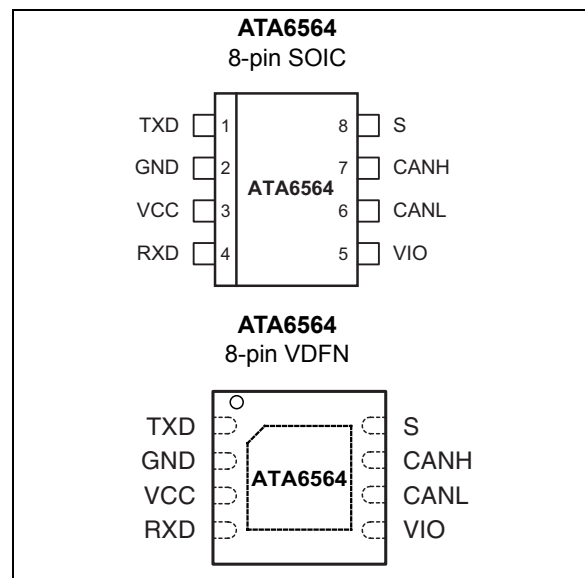
The ATA6564 is a high-speed CAN transceiver that provides an interface between a controller area network (CAN) protocol controller and the physical two-wire CAN bus. The transceiver is designed for high-speed (up to 5 Mbit/s) CAN applications in the automotive industry, providing differential transmit and receive capability to (a microcontroller with) a CAN protocol controller.

It offers improved electromagnetic compatibility (EMC) and electrostatic discharge (ESD) performance, as well as features such as:

- ideal passive behavior to the CAN bus when the supply voltage is off
- direct interfacing to microcontrollers with supply voltages from 3V to 5V

Two operating modes together with the dedicated fail-safe features make the ATA6564 an excellent choice for all types of high-speed CAN networks especially in nodes which do not require a Standby mode with wake-up capability via the bus.

Package Types

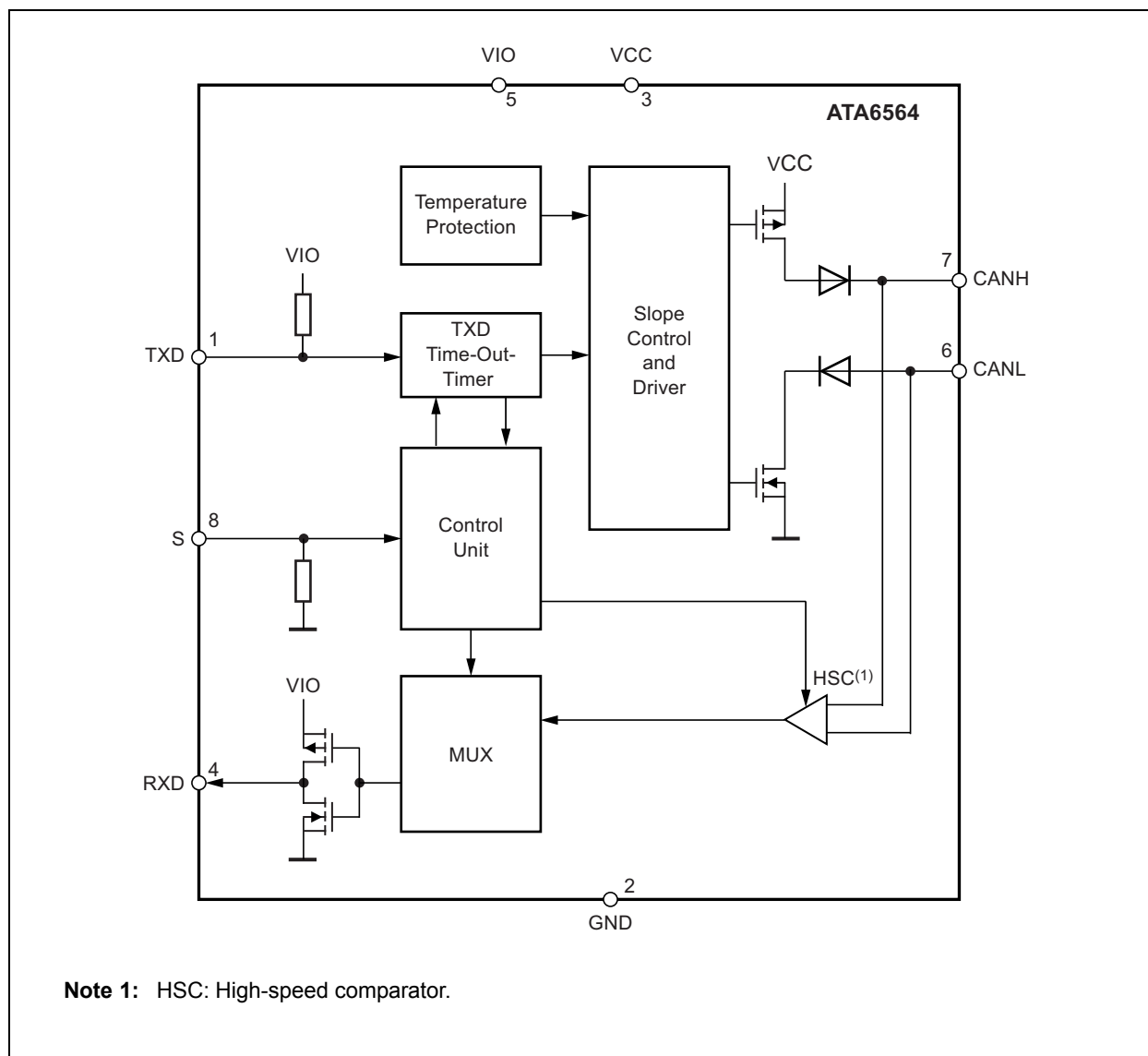


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TABLE 0-1: ATA6564 FAMILY MEMBERS

| Device | Grade 0 | Grade 1 | VDFN8 | SOIC8 | Description |
|---------------|---------|---------|-------|-------|---|
| ATA6564-GAQW0 | x | | | x | Silent mode, VIO - pin for compatibility with 3,3V and 5V microcontroller |
| ATA6564-GBQW0 | x | | x | | Silent mode, VIO - pin for compatibility with 3,3V and 5V microcontroller |
| ATA6564-GAQW1 | | x | | x | Silent mode, VIO - pin for compatibility with 3,3V and 5V microcontroller |
| ATA6564-GBQW1 | | x | x | | Silent mode, VIO - pin for compatibility with 3,3V and 5V microcontroller |

Functional Block Diagram



1.0 DEVICE OVERVIEW

The ATA6564 is a stand-alone high-speed CAN transceiver compliant with the ISO 11898-2, ISO 11898-2: 2016 and SAE J2962-2 CAN standards. It provides very low current consumption in Silent mode.

1.1 Operating Modes

The ATA6564 supports two operating modes: Silent and Normal. These modes can be selected via the S pin. See [Figure 1-1](#) and [Table 1-1](#) for a description of the operating modes.

FIGURE 1-1: OPERATING MODES

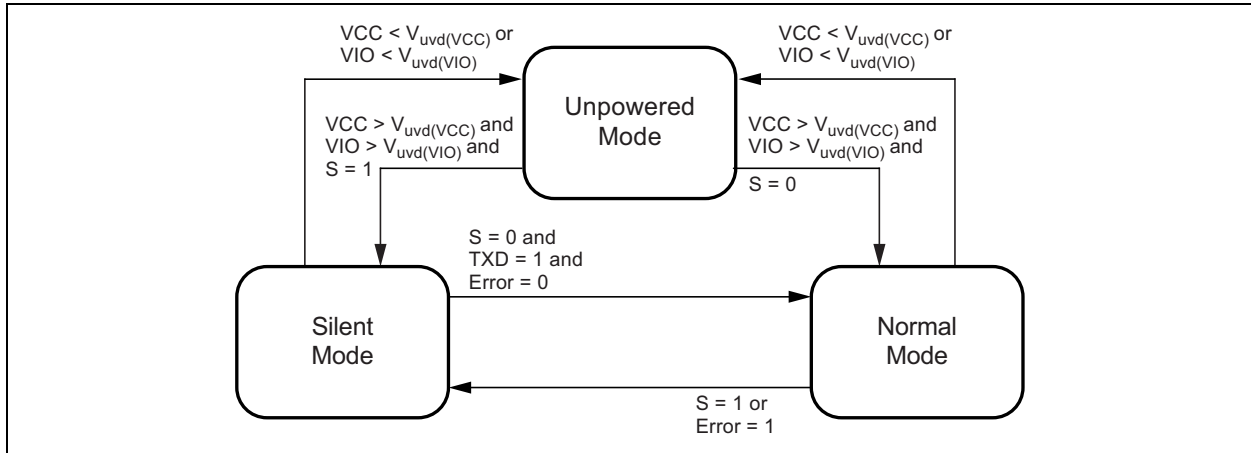


TABLE 1-1: OPERATING MODES

| Mode | Inputs | | Outputs | |
|-----------|------------------|------------------|------------|-----------------------|
| | S | Pin TXD | CAN Driver | Pin RXD |
| Unpowered | x ⁽²⁾ | x ⁽²⁾ | Recessive | Recessive |
| Silent | HIGH | x ⁽²⁾ | Recessive | Active ⁽¹⁾ |
| Normal | LOW | LOW | Dominant | LOW |
| | LOW | HIGH | Recessive | HIGH |

Note 1: LOW if the CAN bus is dominant, HIGH if the CAN bus is recessive.

2: Irrelevant

1.1.1 NORMAL MODE

A low level on the S pin together with a high level on pin TXD selects the Normal mode. In this mode the transceiver is able to transmit and receive data via the CANH and CANL bus lines (see [Section “Functional Block Diagram”](#)). The output driver stage is active and drives data from the TXD input to the CAN bus. The high-speed comparator (HSC) converts the analog data on the bus lines into digital data which is output to pin RXD. The bus biasing is set to $V_{VCC}/2$ and the undervoltage monitoring of VCC is active.

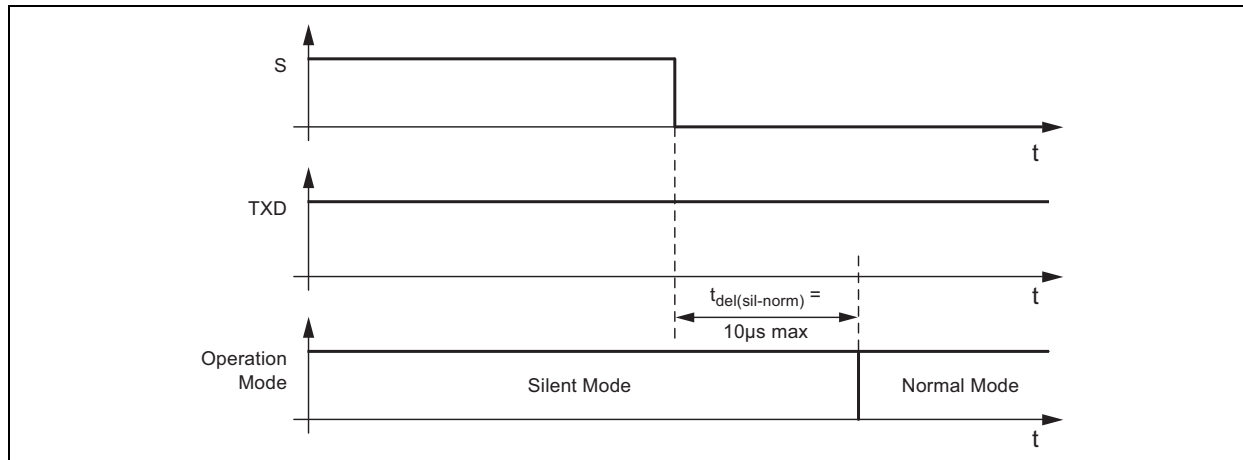
The slope of the output signals on the bus lines is controlled and optimized in a way that guarantees the lowest possible electromagnetic emission (EME).

To switch the device in normal operating mode, set the S pin to low and the TXD pin to high (see [Table 1-1](#) and [Figure 1-2](#)). The S pin provides a pull-down resistor to GND, thus ensuring a defined level if the pin is open.

Please note that the device cannot enter Normal mode as long as TXD is at ground level.

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FIGURE 1-2: SWITCHING FROM SILENT MODE TO NORMAL MODE



1.1.2 SILENT MODE

A high level on the S pin selects Silent mode. This receive-only mode can be used to test the connection of the bus medium. In Silent mode the ATA6564 can still receive data from the bus, but the transmitter is disabled and therefore no data can be sent to the CAN bus. The bus pins are released to recessive state. All other IC functions, including the high-speed comparator (HSC), continue to operate as they do in Normal mode. Silent mode can be used to prevent a faulty CAN controller from disrupting all network communications.

1.2 Fail-safe Features

1.2.1 TXD DOMINANT TIME-OUT FUNCTION

A TXD dominant time-out timer is started when the TXD pin is set to LOW. If the LOW state on the TXD pin persists for longer than $t_{to(dom)TXD}$, the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when the TXD pin is set to high. If the low state on the TXD pin was longer than $t_{to(dom)TXD}$, then the TXD pin has to be set to high longer $4\mu s$ in order to reset the TXD dominant time-out timer.

1.2.2 INTERNAL PULL-UP/PULL-DOWN STRUCTURE AT THE TXD AND S INPUT PINS

The TXD pin has an internal pull-up resistor to V_{IO} and the S pin an internal pull-down resistor to GND. This ensures a safe, defined state in case one or all of these pins are left floating.

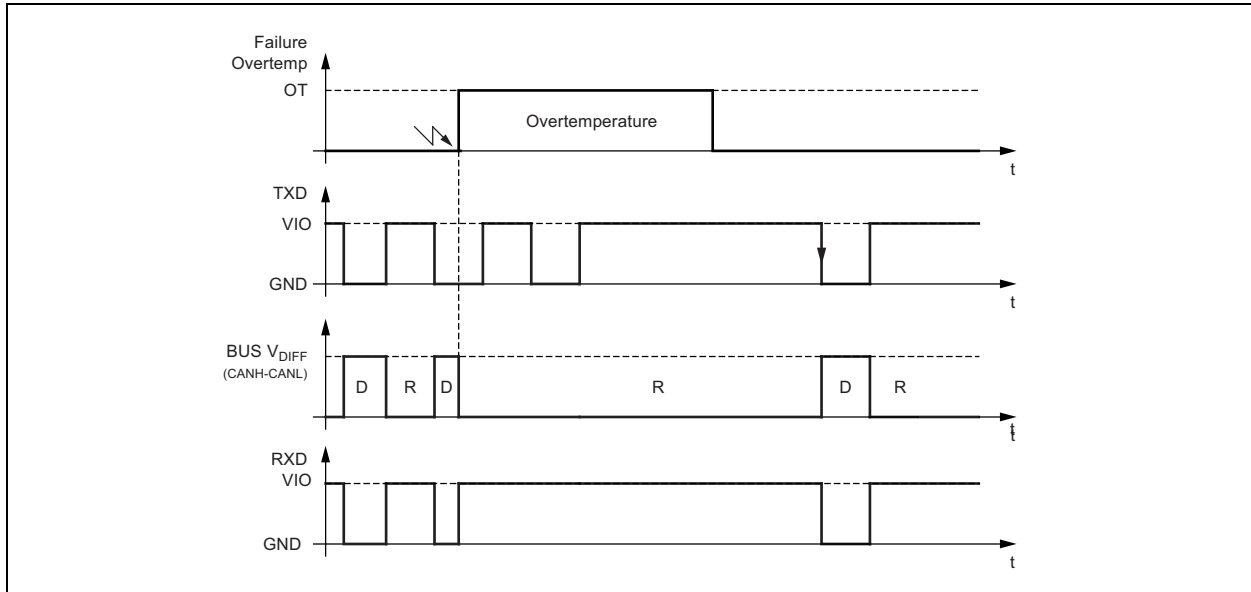
1.2.3 UNDERVOLTAGE DETECTION ON PINS VCC AND VIO

If V_{VCC} or V_{VIO} drop below their respective undervoltage detection levels (V_{uvd(VCC)} and V_{uvd(VIO)}) (see [Section , Electrical Characteristics](#)), the transceiver switches off and disengages from the bus until V_{VCC} and V_{VIO} have recovered. The logic state of the S pin is ignored until the VCC voltage or the VIO voltage has recovered.

1.2.4 OVERTEMPERATURE PROTECTION

The output drivers are protected against overtemperature conditions. If the junction temperature exceeds the shutdown junction temperature, T_{Jsd}, the output drivers are disabled until the junction temperature drops below T_{Jsd} and pin TXD is at high level again. This ensures that output driver oscillations due to temperature drift are avoided.

FIGURE 1-3: RELEASE OF TRANSMISSION AFTER OVERTEMPERATURE CONDITION



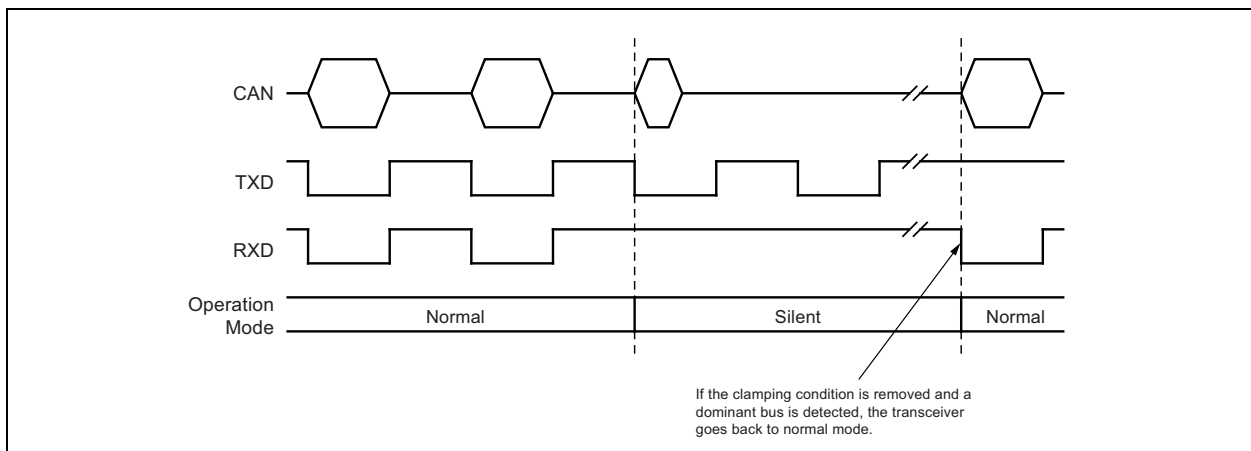
1.2.5 SHORT-CIRCUIT PROTECTION OF THE BUS PINS

The CANH and CANL bus outputs are short-circuit protected, either against GND or a positive supply voltage. A current-limiting circuit protects the transceiver against damage. If the device is heating up due to a continuous short on CANH or CANL, the internal overtemperature protection switches off the bus transmitter.

1.2.6 RXD RECESSIVE CLAMPING

This fail-safe feature prevents the controller from sending data on the bus if its RXD line is clamped to HIGH (e.g., recessive). That is, if the RXD pin cannot signalize a dominant bus condition because it is e.g., shorted to VCC, the transmitter within ATA6564 is disabled to avoid possible data collisions on the bus. In Normal and Silent mode, the device permanently compares the state of the high-speed comparator (HSC) with the state of the RXD pin. If the HSC indicates a dominant bus state for more than t_{RC_det} without the RXD pin doing the same, a recessive clamping situation is detected and the device is forced into Silent mode. This Fail-safe mode is released by either entering Unpowered mode or if the RXD pin is showing a dominant (e.g., LOW) level again.

FIGURE 1-4: RXD RECESSIVE CLAMPING DETECTION



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1.3 Pin Descriptions

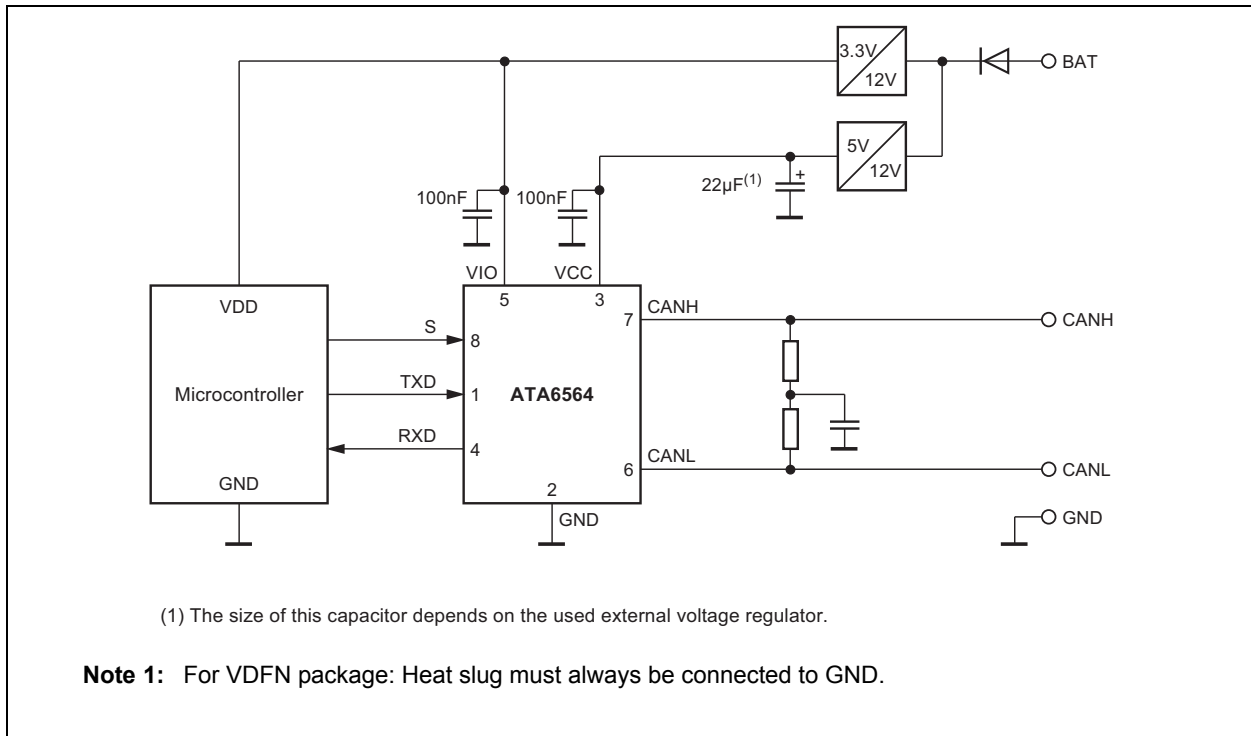
The descriptions of the pins are listed in [Table 1-2](#).

TABLE 1-2: PIN FUNCTION TABLE

| Pin Number | Pin Name | Description |
|------------|-------------------|--|
| 1 | TXD | Transmit data input |
| 2 | GND | Ground supply |
| 3 | VCC | Supply voltage |
| 4 | RXD | Receive data output; reads out data from the bus lines |
| 5 | VIO | Supply voltage for I/O level adapter |
| 6 | CANL | Low-level CAN bus line |
| 7 | CANH | High-level CAN bus line |
| 8 | S | Silent mode control input |
| 9 | EP ⁽¹⁾ | Exposed Thermal Pad: Heat slug, internally connected to the GND pin. |

Note 1: Only for the VDFN package.

1.4 Typical Application



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2.0 ELECTRICAL CHARACTERISTICS

2.1 Absolute Maximum Ratings^(†)

| | |
|--|-----------------|
| DC Voltage at CANH and CANL | -27V to +42V |
| Transient Voltage on CANH and CANL (ISO 7637 part 2) | -150V to +100V |
| Max. differential bus voltage | -5V to +18V |
| DC voltage on all other pins | -0.3V to +5.5V |
| ESD on CANH and CANL pins (IEC 61000-4-2) | ±8 kV |
| ESD (HBM following STM 5.1 with 1.5 kΩ/100 pF) (Pins CANH, CANL to GND) | ±6 kV |
| Component Level ESD (HBM according to ANSI/ESD STM 5.1) JESD22-A114, AEC-Q 100 (002) | ±4 kV |
| CDM ESD STM 5.3.1 | ±750V |
| ESD machine model AEC-Q100-RevF(003) | ±200V |
| Virtual Junction Temperature | -40°C to +175°C |
| Storage Temperature | -55°C to +150°C |

† Notice: Stresses beyond those listed below may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Electrical Specifications: Grade 1: $T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, Grade 0: $T_{amb} = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VCC} = 4.5\text{V}$ to 5.5V ; $V_{VIO} = 2.8\text{V}$ to 5.5V ; $R_L = 60\Omega$, $C_L = 100\text{pF}$, unless otherwise specified. All voltages are defined in relation to ground; positive currents flow into the IC.

| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
|---|--|----------------------|------------|----------------------|---------------|---|
| Supply, Pin VCC | | | | | | |
| Supply Voltage | V_{VCC} | 4.5 | — | 5.5 | V | |
| Supply Current in Silent Mode | I_{VCC_sil} | 1.9 | 2.5 | 3 | mA | Silent Mode, $V_{TXD} = V_{VIO}$ |
| Supply Current in Normal Mode | I_{VCC_rec} I_{VCC_dom} I_{VCC_short} | 2 30 | 50 | 5 70 85 | mA | recessive, $V_{TXD} = V_{VIO}$ dominant, $V_{TXD} = 0\text{V}$ short between CANH and CANL ⁽¹⁾ |
| Undervoltage Detection Threshold on Pin VCC | $V_{uvd(VCC)}$ | 2.75 | — | 4.5 | V | |
| I/O Level Adapter Supply, Pin VIO | | | | | | |
| Supply Voltage on Pin VIO | V_{VIO} | 2.8 | — | 5.5 | V | |
| Supply Current on Pin VIO | I_{VIO_rec} | 10 | 80 | 250 | μA | Normal and Silent Mode recessive, $V_{TXD} = V_{VIO}$ |
| | I_{VIO_dom} | 50 | 350 | 500 | μA | Normal and Silent Mode dominant, $V_{TXD} = 0\text{V}$ |
| Undervoltage Detection Threshold on Pin VIO | $V_{uvd(VIO)}$ | 1.3 | — | 2.7 | V | |
| Mode Control Input, Pin S | | | | | | |
| High-level Input Voltage | V_{IH} | $0.7 \times V_{VIO}$ | — | $V_{VIO} + 0.3$ | V | |
| Low-level Input Voltage | V_{IL} | -0.3 | — | $0.3 \times V_{VIO}$ | V | |
| Pull-down Resistor to GND | R_{pd} | 75 | 125 | 175 | k Ω | $V_S = V_{VIO}$ |
| Low-level Leakage Current | I_L | -2 | — | +2 | μA | $V_S = 0\text{V}$ |
| CAN Transmit Data Input, Pin TXD | | | | | | |
| High-level Input Voltage | V_{IH} | $0.7 \times V_{VIO}$ | — | $V_{VIO} + 0.3$ | V | |
| Low-level Input Voltage | V_{IL} | -0.3 | — | $0.3 \times V_{VIO}$ | V | |
| Pull-up Resistor to VIO | R_{TXD} | 20 | 35 | 50 | k Ω | $V_{TXD} = 0\text{V}$ |
| High-level Leakage Current | I_{TDX} | -2 | — | +2 | μA | Normal Mode, $V_{TXD} = V_{VIO}$ |
| Input Capacitance | C_{TXD} | — | 5 | 10 | pF | Note 3 |
| CAN Receive Data Output, Pin RXD | | | | | | |
| High-level Output Current | I_{OH} | -8 | — | -1 | mA | $V_{RXD} = V_{VIO} - 0.4\text{V}$, $V_{VIO} = V_{VCC}$ |
| Low-level Output Current | I_{OL} | 2 | — | 12 | mA | $V_{RXD} = 0.4\text{V}$, Bus Dominant |
| Bus Lines, Pins CANH and CANL | | | | | | |
| Single Ended Dominant Output Voltage | $V_{O(dom)}$ | 2.75 0.5 | 3.5 1.5 | 4.5 2.25 | V | $V_{TXD} = 0\text{V}$, $t < t_{to(dom)TXD}$ $R_L = 50\Omega$ to 65Ω - pin CANH - pin CANL ⁽¹⁾ |

- Note 1:** 100% correlation tested.
Note 2: Characterized on samples.
Note 3: Design parameter.

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ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Grade 1: $T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, Grade 0: $T_{amb} = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VCC} = 4.5\text{V}$ to 5.5V ; $V_{VIO} = 2.8\text{V}$ to 5.5V ; $R_L = 60\Omega$, $C_L = 100\text{pF}$, unless otherwise specified. All voltages are defined in relation to ground; positive currents flow into the IC.

| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
|--|------------------|------|----------------------|------|------------------|--|
| Transmitter Voltage Symmetry | V_{Sym} | 0.9 | 1 | 1.1 | — | $V_{Sym} = (V_{CANH} + V_{CANL}) / V_{VCC}$ ⁽³⁾ |
| Bus Differential Output Voltage | V_{Diff} | 1.5 | — | 3 | V | $V_{TXD} = 0\text{V}$, $t < t_{to(dom)TXD}$ $R_L = 45\Omega$ to 65Ω |
| | | 1.5 | — | 3.3 | V | $V_{TXD} = 0\text{V}$, $t < t_{to(dom)TXD}$ $R_L = 70\Omega$ ⁽³⁾ |
| | | 1.5 | — | 5 | V | $V_{TXD} = 0\text{V}$, $t < t_{to(dom)TXD}$ $R_L = 2240\Omega$ ⁽³⁾ |
| | | -50 | — | +50 | mV | $V_{VCC} = 4.75\text{V}$ to 5.25V $V_{TXD} = V_{VIO}$, receive, no load |
| Recessive Output Voltage | $V_{O(rec)}$ | 2 | $0.5 \times V_{VCC}$ | 3 | V | Normal and Silent Mode, $V_{TXD} = V_{VIO}$, no load |
| Differential Receiver Threshold Voltage (HSC) | $V_{th(RX)dif}$ | 0.5 | 0.7 | 0.9 | V | Normal and Silent Mode, $V_{cm(CAN)} = -27\text{V}$ to $+27\text{V}$ |
| Differential Receiver Hysteresis Voltage (HSC) | $V_{hys(RX)dif}$ | 50 | 120 | 200 | mV | Normal and Silent Mode, $V_{cm(CAN)} = -27\text{V}$ to $+27\text{V}$ |
| Dominant Output Current | $I_{IO(dom)}$ | -75 | — | -35 | mA | $V_{TXD} = 0\text{V}$, $t < t_{to(dom)TXD}$, $V_{VCC} = 5\text{V}$ - pin CANH, $V_{CANH} = -5\text{V}$ - pin CANL, $V_{CANL} = +40\text{V}$ |
| | | 35 | — | 75 | | |
| Recessive Output Current | $I_{IO(rec)}$ | -5 | — | +5 | mA | Normal and Silent Mode, $V_{TXD} = V_{VIO}$, no load, $V_{CANH} = V_{CANL} = -27\text{V}$ to $+32\text{V}$ |
| Leakage Current | $I_{IO(leak)}$ | -5 | 0 | +5 | μA | $V_{VCC} = V_{VIO} = 0\text{V}$, $V_{CANH} = V_{CANL} = 5\text{V}$ |
| | | -5 | 0 | +5 | μA | $V_{CC} = V_{IO}$ connected to GND with $47\text{k}\Omega$ $V_{CANH} = V_{CANL} = 5\text{V}$ ⁽³⁾ |
| Input Resistance | R_i | 9 | 15 | 28 | $\text{k}\Omega$ | $V_{CANH} = V_{CANL} = 4\text{V}$ |
| | | 9 | 15 | 28 | $\text{k}\Omega$ | $-2\text{V} \leq V_{CANH} \leq +7\text{V}$, $-2\text{V} \leq V_{CANL} \leq +7\text{V}$ ⁽³⁾ |
| Input Resistance Deviation | ΔR_i | -1 | 0 | +1 | % | Between CANH and CANL $V_{CANH} = V_{CANL} = 4\text{V}$ |
| | | -1 | 0 | +1 | % | $-2\text{V} \leq V_{CANH} \leq +7\text{V}$, $-2\text{V} \leq V_{CANL} \leq +7\text{V}$ ⁽³⁾ |
| Differential Input Resistance | $R_{i(dif)}$ | 18 | 30 | 56 | $\text{k}\Omega$ | $V_{CANH} = V_{CANL} = 4\text{V}$ |
| | | 18 | 30 | 56 | $\text{k}\Omega$ | $-2\text{V} \leq V_{CANH} \leq +7\text{V}$, $-2\text{V} \leq V_{CANL} \leq +7\text{V}$ ⁽³⁾ |
| Common-mode Input Capacitance | $C_{i(cm)}$ | — | — | 20 | pF | Note 3 |
| Differential Input Capacitance | $C_{i(dif)}$ | — | — | 10 | pF | Note 3 |

Note 1: 100% correlation tested.

2: Characterized on samples.

3: Design parameter.

ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Grade 1: $T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, Grade 0: $T_{amb} = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$, $V_{VCC} = 4.5\text{V}$ to 5.5V ; $V_{VIO} = 2.8\text{V}$ to 5.5V ; $R_L = 60\Omega$, $C_L = 100\text{pF}$, unless otherwise specified. All voltages are defined in relation to ground; positive currents flow into the IC.

| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
|--|---------------------|------|------|------|---------------|--|
| Differential Bus Voltage Range for RECESSIVE State Detection | V_{Diff_rec} | -3 | — | +0.5 | V | Normal and Silent Mode ⁽³⁾ $-27\text{V} \leq V_{CANH} \leq +27\text{V}$, $-27\text{V} \leq V_{CANL} \leq +27\text{V}$ |
| Differential Bus Voltage Range for DOMINANT State Detection | V_{Diff_dom} | 0.9 | — | 8 | V | Normal and Silent Mode ⁽³⁾ $-27\text{V} \leq V_{CANH} \leq +27\text{V}$, $-27\text{V} \leq V_{CANL} \leq +27\text{V}$ |
| Transceiver Timing, Pins CANH, CANL, TXD, and RXD, see Figure 2-1 and Figure 2-2 | | | | | | |
| Delay Time from TXD to Bus Dominant | $t_{d(TXD-busdom)}$ | 40 | — | 130 | ns | Normal Mode ⁽²⁾ |
| Delay Time from TXD to Bus Recessive | $t_{d(TXD-busrec)}$ | 40 | — | 130 | ns | Normal Mode ⁽²⁾ |
| Delay Time from Bus Dominant to RXD | $t_{d(busdom-RXD)}$ | 20 | — | 100 | ns | Normal and Silent Mode ⁽²⁾ |
| Delay Time from Bus Recessive to RXD | $t_{d(busrec-RXD)}$ | 20 | — | 100 | ns | Normal and Silent Mode ⁽²⁾ |
| Propagation Delay from TXD to RXD | $t_{PD(TXD-RXD)}$ | 40 | — | 210 | ns | Normal Mode $R_L = 60\Omega$, $C_L = 100\text{pF}$ Rising Edge at Pin TXD Falling Edge at Pin TXD |
| | | 40 | — | 200 | ns | |
| | $t_{PD(TXD-RXD)}$ | — | — | 300 | ns | Normal Mode $R_L = 150\Omega$, $C_L = 100\text{pF}$ Rising Edge at Pin TXD ⁽³⁾ Falling Edge at Pin TXD ⁽³⁾ |
| | | — | — | 300 | ns | |
| TXD Dominant Time-out Time | $t_{to(dom)TXD}$ | 0.8 | — | 3 | ms | $V_{TXD} = 0\text{V}$, Normal Mode |
| Delay Time for Normal Mode to Silent Mode Transition | $t_{del(norm-sil)}$ | — | — | 10 | μs | Rising at Pin S ⁽³⁾ |
| Delay Time for Silent Mode to Normal Mode Transition | $t_{del(sil-norm)}$ | — | — | 10 | μs | Falling at Pin S ⁽³⁾ |
| Debouncing Time for Recessive Clamping State Detection | t_{RC_det} | — | 90 | — | ns | $V(CANH-CANL) > 900\text{mV}$ $RXD = \text{HIGH}$ ⁽³⁾ |
| Transceiver Timing for Higher Bit Rates, Pins CANH, CANL, TXD, and RXD, see Figure 2-1 and Figure 2-3, External Capacitor on the RXD Pin $CRXD \leq 20\text{pF}$ | | | | | | |
| Recessive Bit Time on Pin RXD | $t_{Bit(RXD)}$ | 400 | — | 550 | ns | Normal Mode, $t_{Bit(TXD)} = 500\text{ns}$ ⁽¹⁾ |
| | | 120 | — | 220 | ns | |
| Recessive Bit Time on the Bus | $t_{Bit(Bus)}$ | 435 | — | 530 | ns | Normal Mode, $t_{Bit(TXD)} = 500\text{ns}$ ⁽¹⁾ |
| | | 155 | — | 210 | ns | |
| Receiver Timing Symmetry | Δt_{Rec} | -65 | — | +40 | ns | Normal mode, $t_{Bit(TXD)} = 500\text{ns}$ $\Delta t_{Rec} = t_{Bit(RXD)} - t_{Bit(Bus)}$ ⁽¹⁾ |
| | | -45 | — | +15 | ns | |

- Note 1:** 100% correlation tested.
Note 2: Characterized on samples.
Note 3: Design parameter.

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TEMPERATURE SPECIFICATIONS

| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
|---|-------------|------|------|------|-------|------------|
| 8-pin SOIC | | | | | | |
| Thermal Resistance Virtual Junction to Ambient | R_{thvJA} | — | 145 | — | K/W | |
| Thermal Shutdown of the Bus Drivers for ATA6564-GAQW1 (Grade 1) | T_{Jsd} | 150 | 175 | 195 | °C | |
| Thermal Shutdown of the Bus Drivers for ATA6564-GAQW0 (Grade 0) | T_{Jsd} | 160 | 175 | 195 | °C | |
| 8-pin VDFN | | | | | | |
| Thermal Resistance Virtual Junction to Heat Slug | R_{thvJC} | — | 10 | — | K/W | |
| Thermal Resistance Virtual Junction to Ambient, where Heat Slug is soldered to PCB according to JEDEC | R_{thvJA} | — | 50 | — | K/W | |
| Thermal Shutdown of the Bus Drivers for ATA6564-GBQW1 (Grade 1) | T_{Jsd} | 150 | 175 | 195 | °C | |
| Thermal Shutdown of the Bus Drivers for ATA6564-GBQW0 (Grade 0) | T_{Jsd} | 160 | 175 | 195 | °C | |

FIGURE 2-1: TIMING TEST CIRCUIT FOR THE ATA6564 CAN TRANSCEIVER

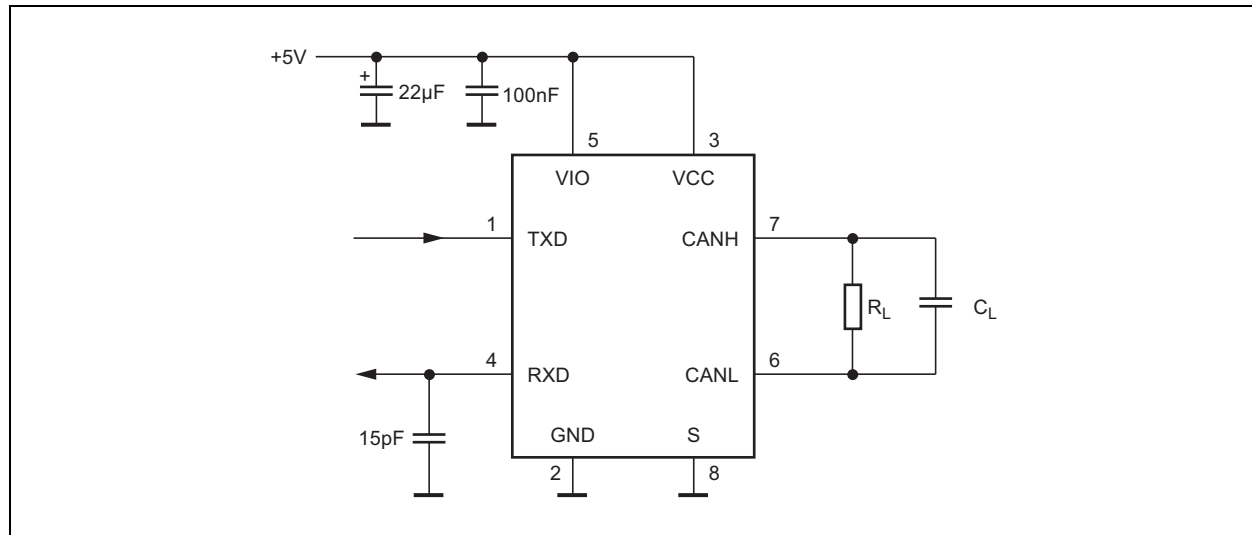


FIGURE 2-2: CAN TRANSCEIVER TIMING DIAGRAM 1

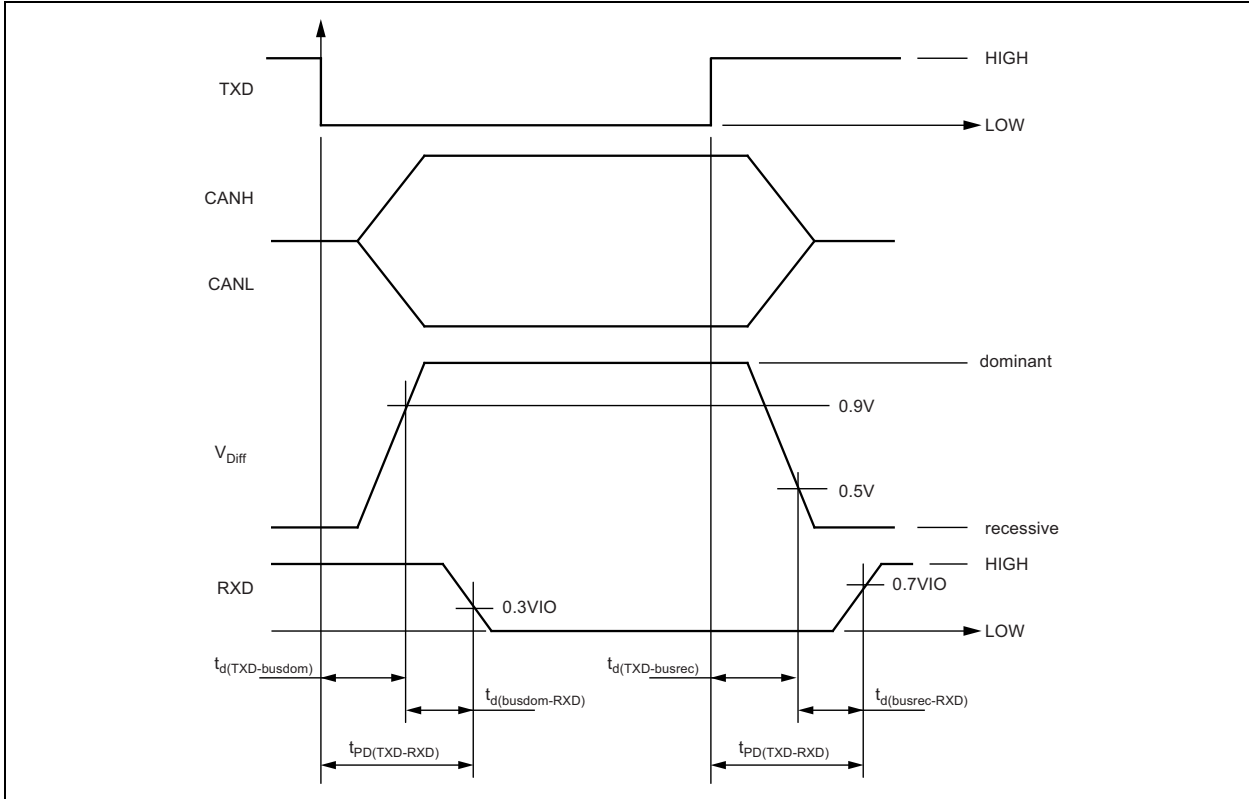
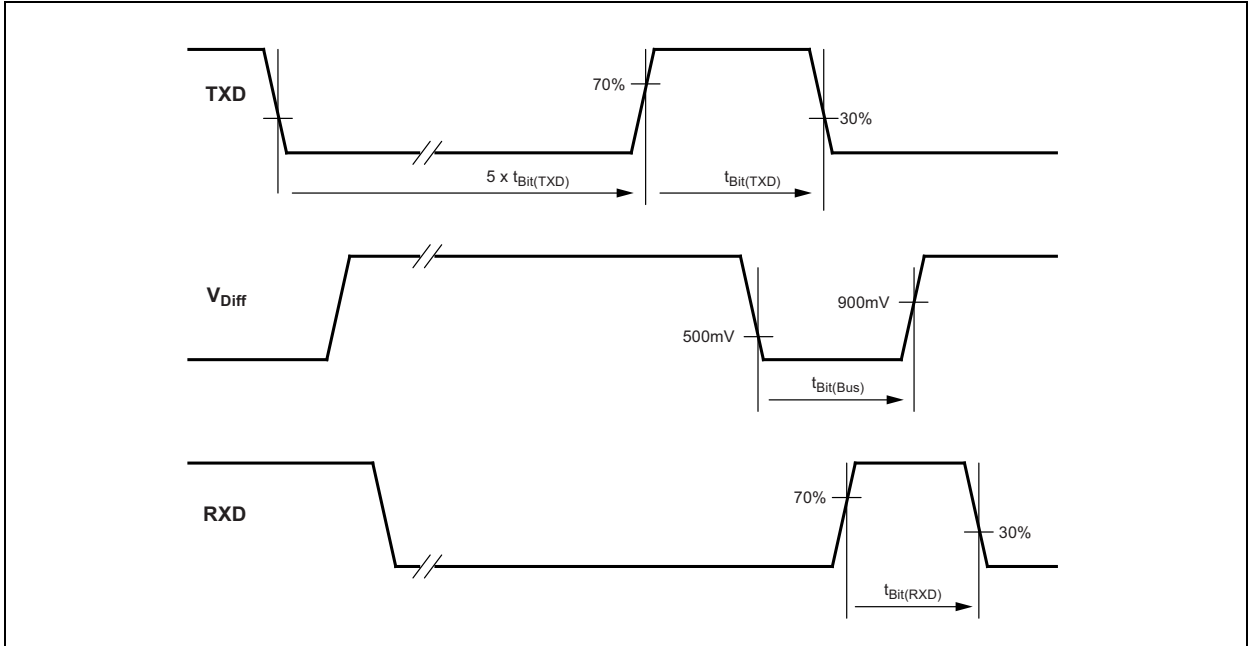


FIGURE 2-3: CAN TRANSCEIVER TIMING DIAGRAM 2

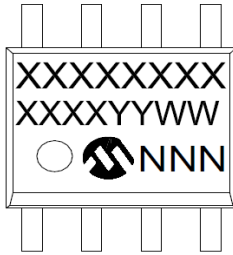


ATA6564

3.0 PACKAGING INFORMATION

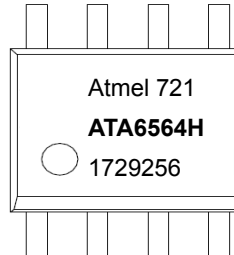
3.1 Package Marking Information

8-Lead SOIC

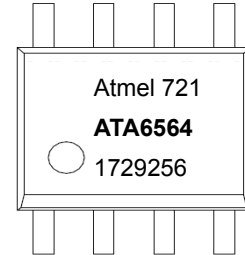


Example

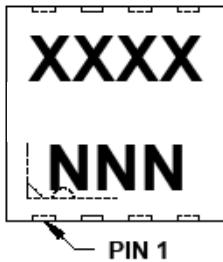
Grade 0



Grade 1

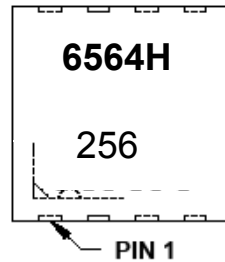


8-Lead VDFN 3 X 3 mm

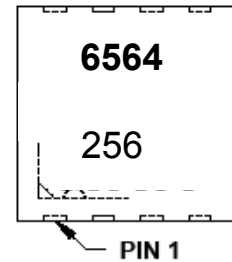


Example

Grade 0



Grade 1

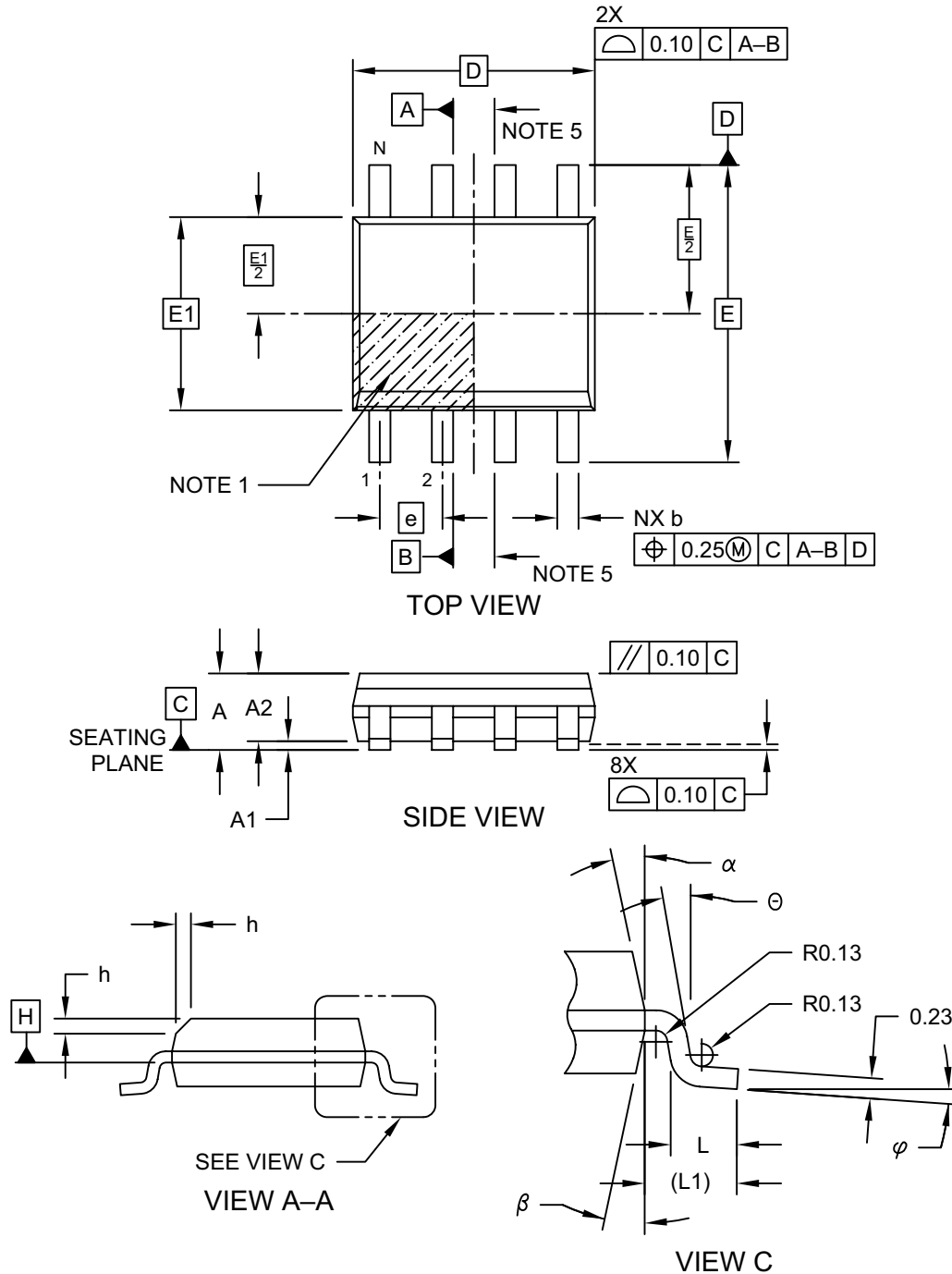


| | | |
|----------------|--------|--|
| Legend: | XX...X | Customer-specific information |
| | Y | Year code (last digit of calendar year) |
| | YY | Year code (last 2 digits of calendar year) |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |
| | (e3) | Pb-free JEDEC designator for Matte Tin (Sn) |
| | * | This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package. |

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

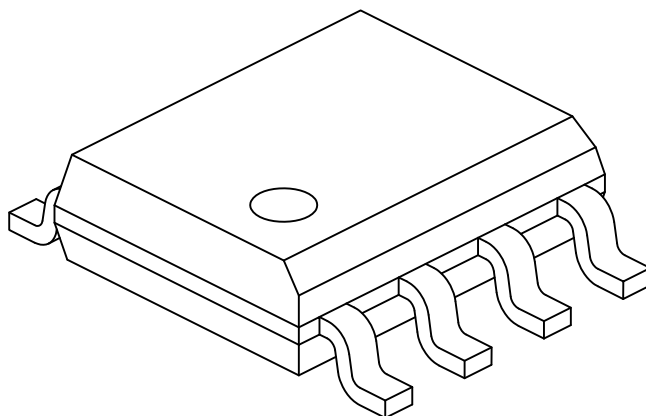


Microchip Technology Drawing No. C04-057-SN Rev D Sheet 1 of 2

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8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | MILLIMETERS | | |
|--------------------------|-----------|-------|-------------|-----|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Pins | N | | 8 | | |
| Pitch | e | | 1.27 BSC | | |
| Overall Height | A | - | - | - | 1.75 |
| Molded Package Thickness | A2 | | 1.25 | - | - |
| Standoff § | A1 | | 0.10 | - | 0.25 |
| Overall Width | E | | 6.00 BSC | | |
| Molded Package Width | E1 | | 3.90 BSC | | |
| Overall Length | D | | 4.90 BSC | | |
| Chamfer (Optional) | h | | 0.25 | - | 0.50 |
| Foot Length | L | | 0.40 | - | 1.27 |
| Footprint | L1 | | 1.04 REF | | |
| Foot Angle | φ | | 0° | - | 8° |
| Lead Thickness | c | | 0.17 | - | 0.25 |
| Lead Width | b | | 0.31 | - | 0.51 |
| Mold Draft Angle Top | α | | 5° | - | 15° |
| Mold Draft Angle Bottom | β | | 5° | - | 15° |

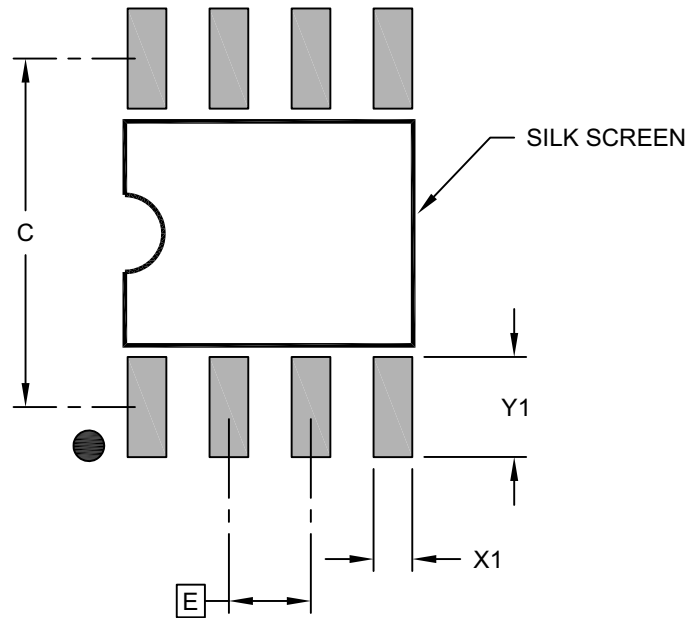
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-057-SN Rev D Sheet 2 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|-------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 1.27 BSC | | |
| Contact Pad Spacing | C | | 5.40 | |
| Contact Pad Width (X8) | X1 | | | 0.60 |
| Contact Pad Length (X8) | Y1 | | | 1.55 |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

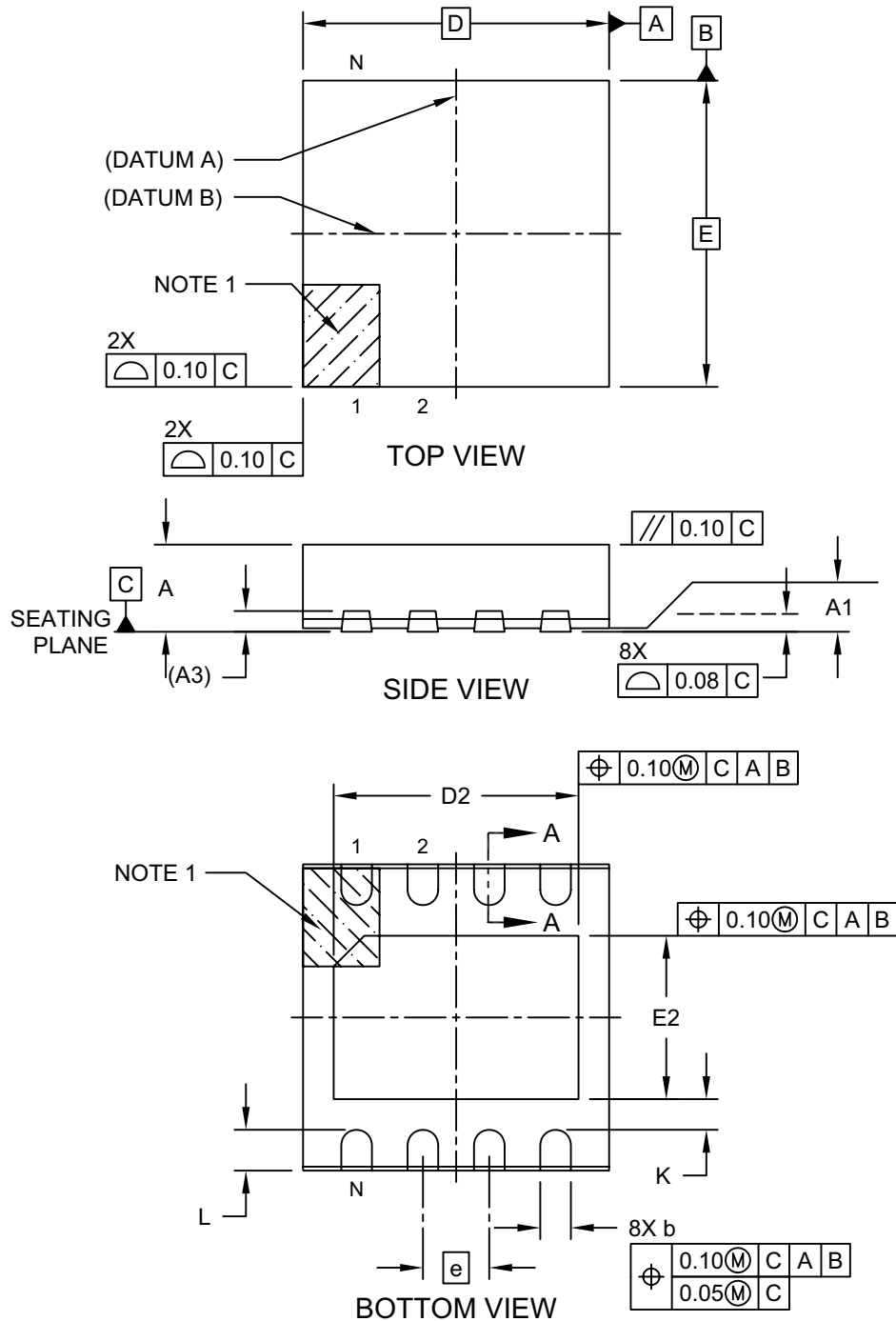
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2057-SN Rev B

ATA6564

8-Lead Very Thin Plastic Dual Flat, No Lead Package (Q8B) - 3x3 mm Body [VDFN] With 2.40x1.60 mm Exposed Pad and Stepped Wettable Flanks

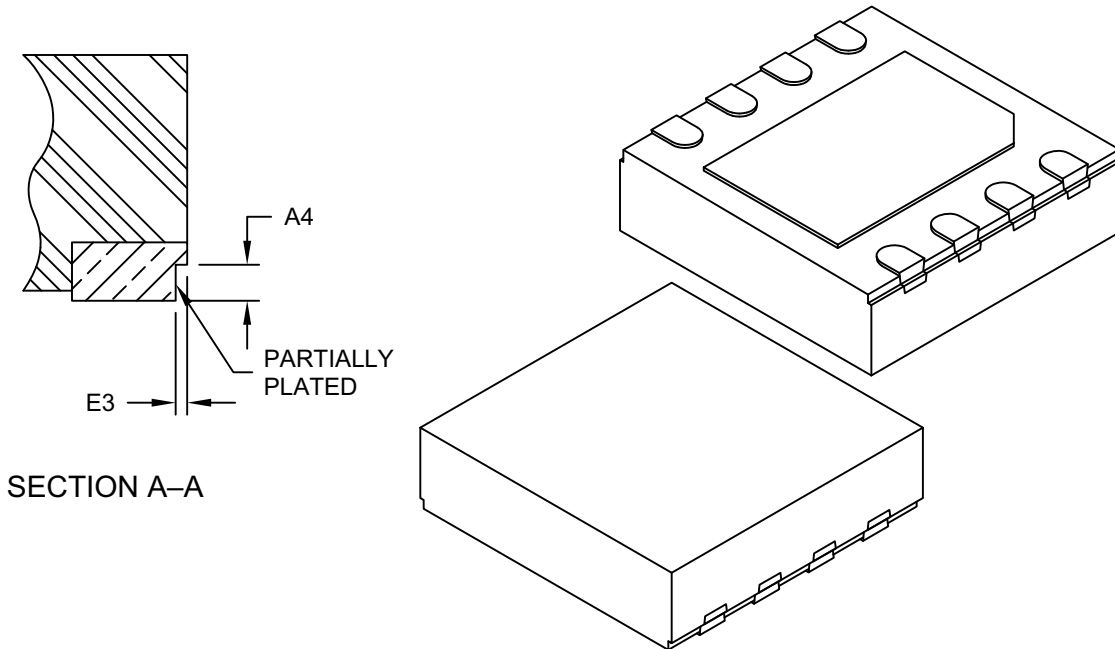
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-21358 Rev B Sheet 1 of 2

8-Lead Very Thin Plastic Dual Flat, No Lead Package (Q8B) - 3x3 mm Body [VDFN] With 2.40x1.60 mm Exposed Pad and Stepped Wettable Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits | Units | MILLIMETERS | | |
|-------------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Terminals | N | 8 | | |
| Pitch | e | 0.65 BSC | | |
| Overall Height | A | 0.80 | 0.85 | 0.90 |
| Standoff | A1 | 0.00 | 0.03 | 0.05 |
| Terminal Thickness | A3 | 0.203 REF | | |
| Overall Length | D | 3.00 BSC | | |
| Exposed Pad Length | D2 | 2.30 | 2.40 | 2.50 |
| Overall Width | E | 3.00 BSC | | |
| Exposed Pad Width | E2 | 1.50 | 1.60 | 1.70 |
| Terminal Width | b | 0.25 | 0.30 | 0.35 |
| Terminal Length | L | 0.35 | 0.40 | 0.45 |
| Terminal-to-Exposed-Pad | K | 0.20 | - | - |
| Wettable Flank Step Cut Depth | A4 | 0.10 | 0.13 | 0.15 |
| Wettable Flank Step Cut Width | E3 | - | - | 0.04 |

Notes:

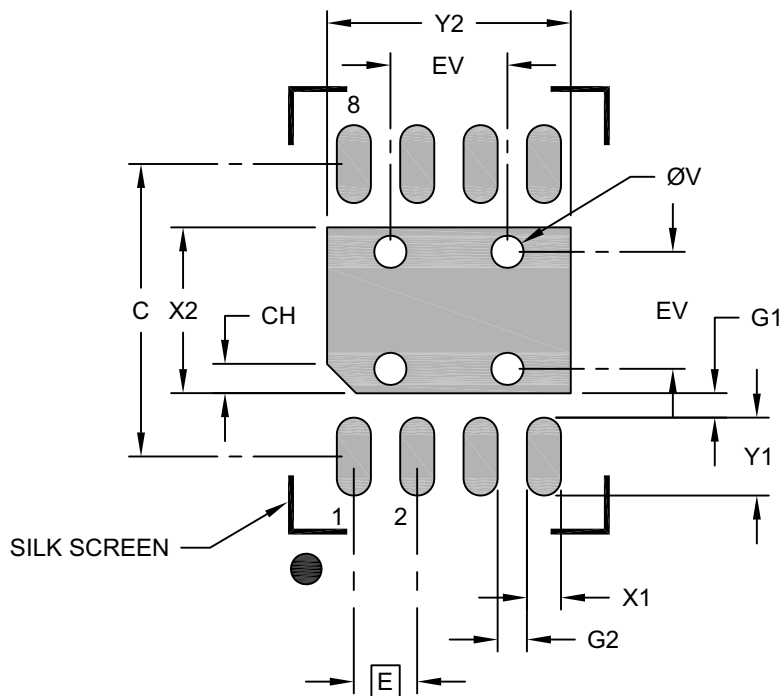
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-21358 Rev B Sheet 2 of 2

ATA6564

8-Lead Very Thin Plastic Dual Flat, No Lead Package (Q8B) - 3x3 mm Body [VDFN] With 2.40x1.60 mm Exposed Pad and Stepped Wettable Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|---------------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.65 BSC | | |
| Optional Center Pad Width | X2 | | | 1.70 |
| Optional Center Pad Length | Y2 | | | 2.50 |
| Contact Pad Spacing | C | | 3.00 | |
| Contact Pad Width (X8) | X1 | | | 0.35 |
| Contact Pad Length (X8) | Y1 | | | 0.80 |
| Contact Pad to Center Pad (X8) | G1 | 0.20 | | |
| Contact Pad to Contact Pad (X6) | G2 | 0.20 | | |
| Pin 1 Index Chamfer | CH | 0.20 | | |
| Thermal Via Diameter | V | | 0.33 | |
| Thermal Via Pitch | EV | | 1.20 | |

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-23358 Rev B

APPENDIX A: REVISION HISTORY

Revision B (July 2017)

The following is the list of modifications:

1. Added the new device ATA6564-GBQW0 and updated the related information across the document.
2. Updated [Table 0-1](#).
3. Corrected [Section “Electrical Characteristics”](#).
4. Updated [Section “Temperature Specifications”](#).
5. Updated the VDFN8 package drawing and added a Grade 0 package example to [Section 3.1, Package Marking Information](#).
6. Added a ATA6564-GBQW0 example to [Section “Product Identification System”](#).
7. Various typographical edits.

Revision A (June 2017)

- Original Release of this Document.

ATA6564

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

| <u>PART NO.</u> | <u>XX</u> | <u>IXI⁽¹⁾</u> | <u>X</u> | <u>X</u> |
|---|-----------|--------------------------|--|-------------------|
| Device | Package | Tape and Reel Option | Package directives classification | Temperature Range |
| Device: | ATA6564: | | High-speed CAN Transceiver with Silent Mode CAN FD Ready | |
| Package: | GA = | | 8-Lead SOIC | |
| | GB = | | 8-Lead VDFN | |
| Tape and Reel Option: | Q = | | 330 mm diameter Tape and Reel | |
| Package directives classification: | W = | | Package according to RoHS ⁽²⁾ | |
| Temperature Range: | 0 = | | Temperature Grade 0 (-40°C to +150°C) | |
| | 1 = | | Temperature Grade 1 (-40°C to +125°C) | |

| | |
|-------------------|---|
| Examples: | |
| a) ATA6564-GAQW0: | ATA6564, 8-Lead SOIC, Tape and Reel, Package according to RoHS, Temperature Grade 0 |
| b) ATA6564-GBQW0: | ATA6564, 8-Lead VDFN, Tape and Reel, Package according to RoHS, Temperature Grade 0 |
| c) ATA6564-GAQW1: | ATA6564, 8-Lead SOIC, Tape and Reel, Package according to RoHS, Temperature Grade 1 |
| d) ATA6564-GBQW1: | ATA6564, 8-Lead VDFN, Tape and Reel, Package according to RoHS, Temperature Grade 1 |

| | |
|----------------|--|
| Note 1: | Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option. |
| Note 2: | RoHS compliant, Maximum concentration value of 0.09% (900 ppm) for Bromine (Br) and Chlorine (Cl) and less than 0.15% (1500 ppm) total Bromine (Br) and Chlorine (Cl) in any homogeneous material. Maximum concentration value of 0.09% (900 ppm) for Antimony (Sb) in any homogeneous material. |

ATA6564

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

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